

### UTT15P06G-TN3-R-VB Datasheet

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)		
- 60	0.061 at V <sub>GS</sub> = - 10 V	- 30	10		
- 80	0.072 at V <sub>GS</sub> = - 4.5 V	- 25	10		

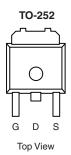
#### **FEATURES**

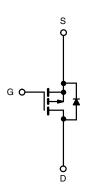
- Trench Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 2$	25 °C, unless othe	rwise noted			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	l-	- 30		
Continuous Diain Current (1) = 175 C)	T <sub>C</sub> = 100 °C	ID	- 25		
Pulsed Drain Current	I <sub>DM</sub>	- 30	A		
Continuing Source Current (Diode Conduction)	I <sub>S</sub>	- 20			
Avalanche Current	I <sub>AS</sub>	- 20	1		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	7.2	mJ	
Maximum Daylar Dissination	T <sub>C</sub> = 25 °C	34 <sup>a</sup>		w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	4 <sup>b</sup>	7 **	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
hunghian ta Ambianto	t ≤ 10 sec	R <sub>thJA</sub>	20	25		
Junction-to-Ambient <sup>D</sup>	Steady State	□thJA	62	75	°C/W	
Junction-to-Case		R <sub>thJC</sub>	5	6		

#### Notes:

- a. See SOA curve for voltage derating.
- b. Surface Mounted on 1" x 1" FR-4 boad.

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Parameter	Symbol	Test Conditions	Min	Typ <sup>a</sup>	Max	Unit	
Static							
Drain-Source Breakdown Voltage V <sub>(BR)DSS</sub>		$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60		V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0	- 2.0	- 3.0	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μΑ	
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			- 150		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 10			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A	0.061				
	_	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 125 °C		0.100			
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 175 °C		0.150	Ω		
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2 A		0.072			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5 A		8		S	
Dynamic	•			•			
Input Capacitance	C <sub>iss</sub>			1000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Gate Charge	$Q_g$			10			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -8.4 \text{ A}$		2.1		nC	
Gate-Drain Charge	Q <sub>gd</sub>			3.2			
Gate Resistance	$R_{g}$	f = 1 MHz	8.0			Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			6			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, R_L = 3.57 \Omega$		15		20	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong$ - 8.4 A, $V_{GEN} =$ - 10 V, $R_G = 2.5 \Omega$		16		ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	1		8			
Source-Drain Diode Ratings and Cha	aracteristics	(T <sub>C</sub> = 25 °C) <sup>b</sup>					
Pulsed Current	I <sub>SM</sub>				- 30	Α	
Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = - 2 A, V <sub>GS</sub> = 0 V		- 0.9	- 1.3	V	
Reverse Recovery Time	t <sub>rr</sub>	L = 9 A di/dt = 100 A/::2		50		ns	
Reverse Recovery Time	Q <sub>rr</sub>	I <sub>F</sub> = - 8 A, di/dt = 100 A/μs		80		nC	

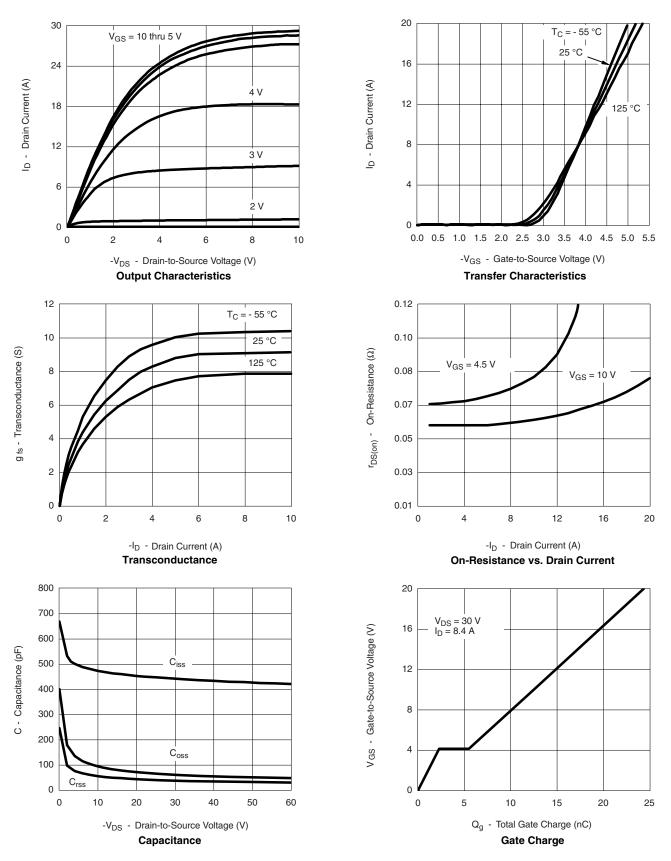
#### Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

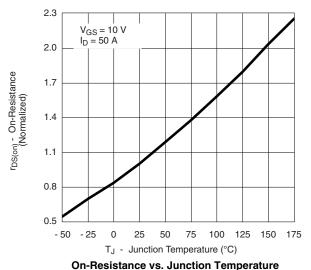


#### TYPICAL CHARACTERISTICS 25 °C unless noted

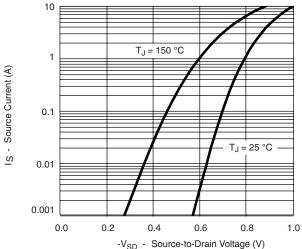




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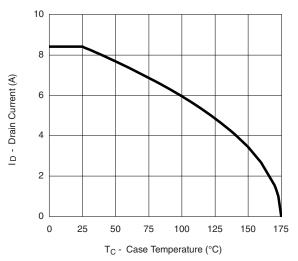




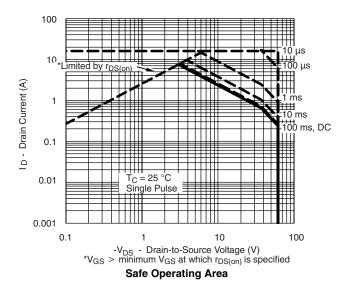
Source-Drain Diode Forward Voltage

#### THERMAL RATINGS

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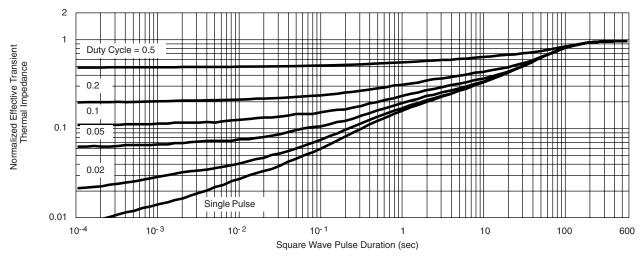
**Drain Current vs. Case Temperature** 



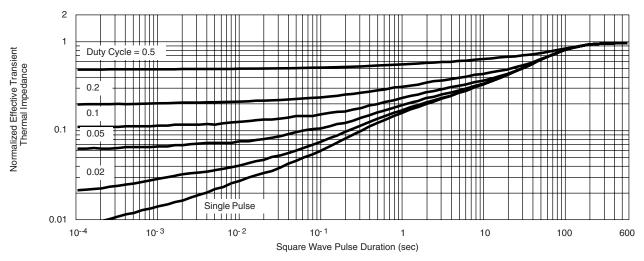
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#### THERMAL RATINGS



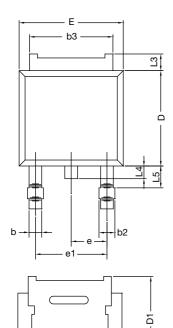
Normalized Thermal Transient Impedance, Junction-to-Ambient

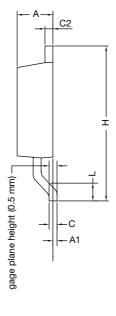


Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA CASE OUTLINE**





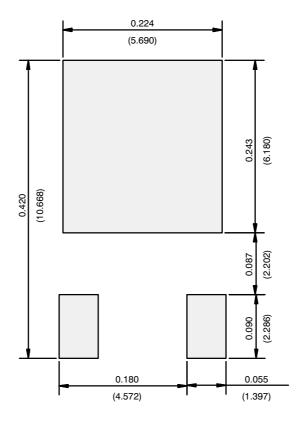
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
Α	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
С	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	5.21	-	0.205	-
Е	6.35	6.73	0.250	0.265
E1	4.32	1	0.170	1
Н	9.40	10.41	0.370	0.410
е	2.28	BSC 0.090 BS		BSC
e1	4.56	BSC	0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.14	1.52	0.045	0.060
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347				

#### Note

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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